

| | Type | L # | Hits | Search Text | DBs | Time Stamp |
|---|------|-----|------|---|---|---------------------|
| 1 | BRS | L1 | 9122 | (laser (light adj emitting adj diode)) and driver and (superstrate cover) | USPAT; EPO; JPO; DERWENT; IBM_TD B | 2002/11/07 15:16 |
| 2 | BRS | L2 | 503 | 1 and (silicon adj substrate) | USPAT; EPO; JPO; DERWENT; IBM_TD B | 2002/11/07 15:10 |
| 3 | BRS | L3 | 79 | 2 and hybrid | USPAT; EPO; JPO; DERWENT; IBM_TD B | 2002/11/07 15:10 |
| 4 | BRS | L4 | 0 | ((laser (light adj emitting adj diode)) adj array) and (handle adj substrate) | USPAT; EPO; JPO; DERWENT; IBM_TD B | 2002/11/07 15:17 |
| 5 | BRS | L5 | 35 | ((laser (light adj emitting adj diode))) and (handle adj substrate) | USPAT; EPO; JPO; DERWENT; IBM_TD B | 2002/11/07 15:17 |

| | Type | L # | Hits | Search Text | DBs | Time Stamp |
|---|------|-----|------|--|---|---------------------|
| 1 | BRS | L1 | 96 | (handle adj wafer) and laser | USPAT; EPO; JPO; DERWEN T; IBM_TD B | 2002/11/07 10:05 |
| 2 | BRS | L4 | 2048 | 257/773-778.ccls. and via | USPAT; EPO; JPO; DERWEN T; IBM_TD B | 2002/11/07 10:45 |
| 3 | BRS | L5 | 96 | 4 and interposer | USPAT; EPO; JPO; DERWEN T; IBM_TD B | 2002/11/07 11:08 |
| 4 | BRS | L6 | 586 | (372/43-50.ccls. 257/80-103.ccls.) and array and (carrier) | USPAT; EPO; JPO; DERWEN T; IBM_TD B | 2002/11/07 11:45 |
| 5 | BRS | L7 | 162 | (372/43-50.ccls. 257/80-103.ccls.) and array and modulator | USPAT; EPO; JPO; DERWEN T; IBM_TD B | 2002/11/07 12:27 |
| 6 | BRS | L8 | 5468 | (372/43-50.ccls. 257/80-103.ccls.) and (singulate cut separate groove channel trench) | USPAT; EPO; JPO; DERWEN T; IBM_TD B | 2002/11/07 11:53 |

| | Type | L # | Hits | Search Text | DBs | Time Stamp |
|---|------|-----|------|---|---|---------------------|
| 7 | BRS | L9 | 1264 | 8 and array | USPAT; EPO; JPO; DERWEN T; IBM_TD B | 2002/11/07 11:54 |
| 8 | BRS | L10 | 359 | (372/43-50.ccls. 257/80-103.ccls.) and hybrid | USPAT; EPO; JPO; DERWEN T; IBM_TD B | 2002/11/07 12:28 |